

## Product Change Notification

Document No.

PCN-A-20250219

Revision

1.0

**PCN TOPIC:**

Thermal Design Enhancement for 10.4" Adler Lake Series Panel PC.

**PCN Type:**

Product Improvement.

**Change Detail Descriptions:**

For Panel PCs equipped with Alder Lake or newer CPUs, an aluminum heat sink has been implemented on the rear cover to improve overall thermal efficiency. This enhancement is necessary due to the compact size of the 10.4" series, ensuring system stability and optimal heat management.

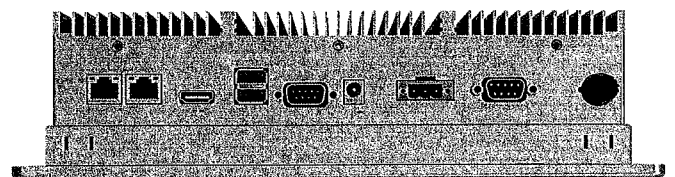
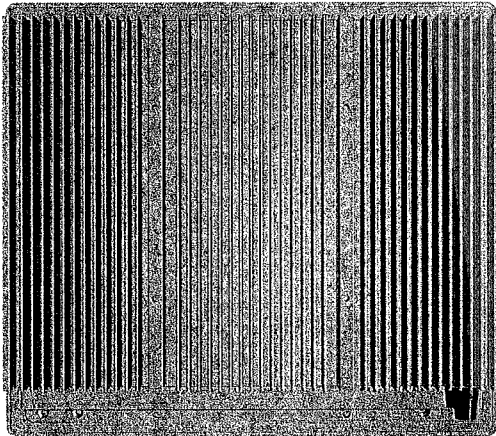
**Change and Impact:**

Critical Change:

Form: outside dimension changes

General Change:

*New*



**Impacts:**

BIOS change: No

Device Driver changes: No

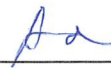
Software: OS image changes: No

Board changes: No

Mechanical changes: Yes

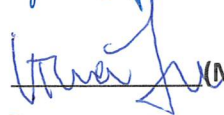
# Impacted Product List:

Product line	Model Name
10.4" Panel PC	R10IAD3S-PPT2
	R10IAD3S-CHT2
	R10IAD3S-IPT2
	R10IAD3S-PMT2
	R10IAD3S-OFT2

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If you have any further questions or clarification needed for this PCN, please feel free to contact Winmate Reseller or your contact windows of Winmate Sales Representatives. Or you can feedback to [Sales@winmate.com.tw](mailto:Sales@winmate.com.tw) email.